



Quick Reference

Search by part #

Check distributor part inventory

Products

Browse Products

-By Device -

-By Product Line-

-Attachment Methods

-Interface Materials-

-Accessories -

Useful Links

- [Building a Part #](#)
- [Catalog Request](#)
- [Directions](#)
- [Find Distributor](#)
- [Find Sales Rep](#)
- [How to Order?](#)
- [MSDS Safety Sheets](#)
- [Part # Cross Ref](#)
- [Quote Request](#)
- [RoHS Initiative](#)
- [Sample Request](#)

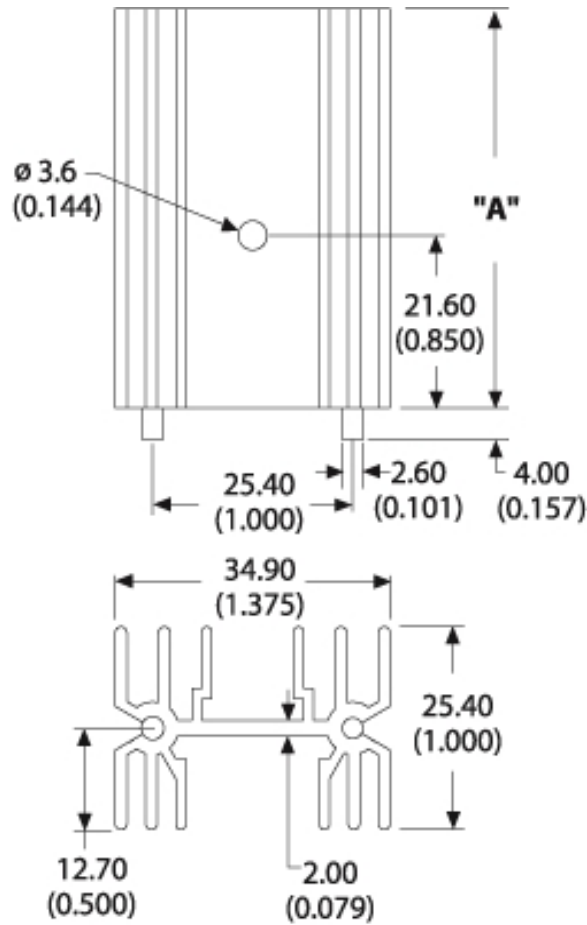
For use with TO -220/TO -218/TO -247 packages

Printer friendly version

Part Number - BW50 -4G

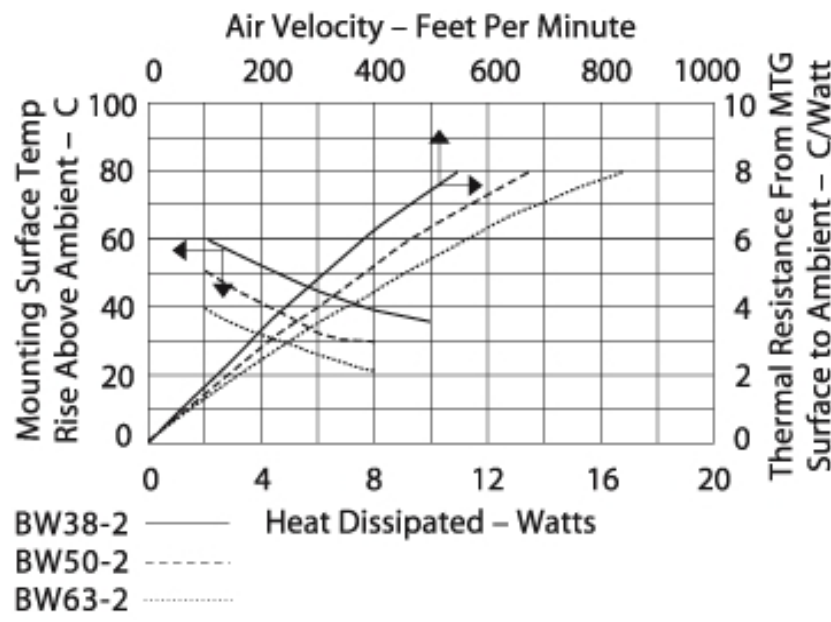


Mechanical Outline Drawing



A Dim 50.00

Thermal Curves



Thermal Resistance	5.80
---------------------------	------

Thermal resistance value is based on a 75°C rise in natural convection

Product Information

Part #	Description	Finish	Board Mounting
BW50 - 4G	Wide extruded heat sink with unequal channel widths and device mounting hole	Black Anodize	N/A

This non -electronic component is functionally unaffected by the normal soldering or reflow processes used for semiconductor circuits. The heat resistance time or heat resistance temperature is not applicable for the component.

Not Exactly what you need?

We offer several options for those applications which require a more unique solution. For slight modifications of this part or other attachment options, finishes, and interface materials, contact your [local representative](#) . Challenge us with your thermal requirements - we can design custom solutions.